

# **AP22817BKBWT-7 Datasheet**

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DiGi Electronics Part Number Manufacturer Manufacturer Product Number Description Detailed Description AP22817BKBWT-7-DG Diodes Incorporated AP22817BKBWT-7 USBPOWERSWITCHTSOT25T&R3K Power Switch/Driver 1:1 N/P-Channel 1.5A TSOT-2 5

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# Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
AP22817BKBWT-7	Diodes Incorporated
Series:	Product Status:
	Active
Switch Type:	Number of Outputs:
USB Switch	1
Ratio - Input:Output:	Output Configuration:
1:1	High Side
Output Type:	Interface:
N/P-Channel	On/Off
Voltage - Load:	Voltage - Supply (Vcc/Vdd):
2.7V ~ 5.5V	Not Required
Current - Output (Max):	Rds On (Typ):
1.5A	75mOhm
Input Type:	Features:
Inverting	Load Discharge
Fault Protection:	Operating Temperature:
Current Limiting (Fixed), Over Temperature, Reverse C	Current, Short Circuiងዐፄø៤សេះទ (TA)
Grade:	Qualification:
Automotive	AEC-Q100
Mounting Type:	Supplier Device Package:
Surface Mount	TSOT-25
Package / Case:	Base Product Number:
SOT-23-5 Thin, TSOT-23-5	AP22817

# **Environmental & Export classification**

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8542.39.0001	





# AP22816/17/18

## 1.0A/1.5A/2.0A SINGLE CHANNEL POWER DISTRIBUTION LOAD SWITCH

## Description

The DIODES<sup>™</sup> AP22816/17/18 is a single-channel, current-limited, integrated high-side power switch optimized for Universal Serial Bus (USB) and other hot-swap applications. The family of devices complies with USB standards and is available with both polarities of enable input.

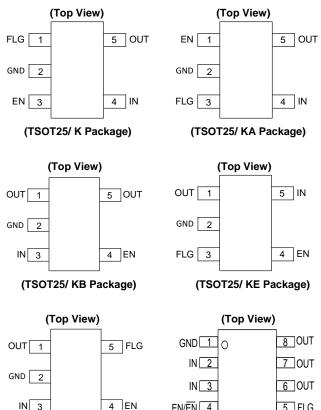
The device has fast short-circuit response time for improved overall system robustness, and has an integrated output discharge function to ensure completely controlled discharging of the output voltage capacitor. They provide a complete protection solution for applications subject to heavy capacitive loads and the prospect of short circuit, and offer reverse current blocking, overcurrent, overtemperature and short-circuit protection, as well as controlled rise time and undervoltage lockout functionality. A 6ms deglitch capability on the open-drain flag output prevents false overcurrent reporting and does not require any external components.

The AP22816/17/18 is available in the standard Green and RoHS compliant TSOT25 and MSOP-8 packages.

## Features

- Input Voltage Range: 2.7V to 5.5V
- 75mΩ On-resistance
- Built-in Soft-start with 0.6ms Typical Rise Time
- Fault Report (FLG) with Blanking Time (6ms Typ.)
- ESD Protection: 2kV HBM, 500V CDM
- Logic Level Enable Pin: Available with Active-high or Active-low Versions
- Protections:
  - Overcurrent Protection with Auto Recovery .
  - Short-Circuit Protection with Auto Recovery
  - Overtemperature Protection with Auto Recovery
  - Output Reverse Current / Voltage Protection
- Thermally-Efficient Low Profile Package
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals
  - TSOT-25: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (e3)
  - MSOP-8: Finish Matte Tin Plated Leads, Solderable per . MIL-STD-202, Method 208 (e3)
- Weight:
  - TSOT25: 0.013 grams (Approximate) .
  - MSOP-8: 0.027grams(Approximate)
  - UL Recognized, File Number E322375
- IEC60950-1 CB Scheme Certified
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/guality/product-definitions/

## **Pin Assignments**



## Applications

- Integrated load switches in Ultrabook PCs
- Power up/down sequencing in Ultrabook PCs
- Notebooks
- Netbooks
- Set-top boxes
- SSD (solid state drives)
- Consumer electronics
- Tablet PCs
- Telecom systems

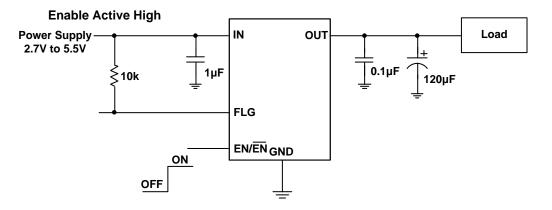
- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. Notes: 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4 EN EN/EN 4 5 FLG (TSOT25/ KC Package) MSOP-8





# **Typical Applications Circuit**



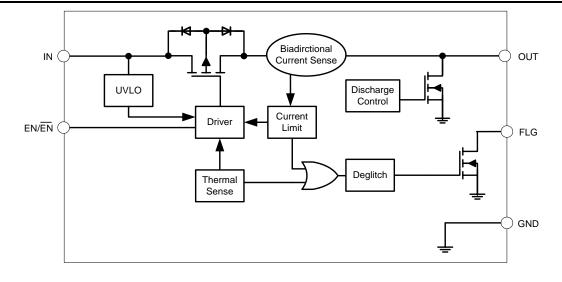
Note: If  $1\mu F$  input cap. Will lead to large  $V_{IN}$  spike, it's recommended to use  $10\mu F$  capacitor instead.

# **Pin Descriptions**

Pin Nu	Pin Number		Function	
TSOT25	MSOP-8	Pin Name	Function	
5(K/KA) 1, 5(KB)	6, 7, 8	OUT	Voltage Output Pin, connect a 0.1µF bypass capacitor and a high-value capacitor to GND, close to IC. (At least 10µF in USB applications.)	
1(KE)				
2	1	GND	Ground pin of the circuitry	
1(K) 3(KA/KE) 5(KC)	5	FLG	Overcurrent and Overtemperature fault report; Open-Drain flag is active-low when triggered.	
3(K)			Enable input	
1(KA)	4	EN/EN	AP22816A/17A/18A: Active-High	
4(KB/KE)			AP22816B/17B/18B: Active-Low	
4(K/KA) 3(KB) 5(KE)	2, 3	IN	Voltage Input Pin, connect a $1\mu F$ low ESR capacitor to GND, close to IC.	



# **Functional Block Diagram**



## Absolute Maximum Ratings (@ T<sub>A</sub> = +25°C, unless otherwise specified.) (Note 4)

Sy	mbol	Parameter		Ratings	Units
	HBM	Human Body ESD Protection		2000	V
ESD	CDM	Charged Device Model ESD Protection		500	V
LOD	IEC System Level	Surges per IEC61000-4-2. 1999 Applied to Terminals of EVM (Note 6)	15	kV	
	Vin	Input Voltage		-0.3 to 6.0	V
V	′оит	Output Voltage		-0.3 to (V <sub>IN</sub> +0.3)	V
V	EN/EN	Enable Voltage		-0.3 to (V <sub>IN</sub> +0.3)	V
	IL	Load Current		Internal Limited	°C
T,	l(max)	Maximum Junction Temperature		+150	°C
	Γ <sub>ST</sub>	Storage Temperature		-65 to +150	°C
R <sub>0JA</sub> Thermal Resistance, Junction to Ambient Thermal Resistance, Junction to Case		MSOP-8 (Note 5, 7)	165		
		Thermal Resistance, Junction to Case	TSOT25 (Note 6, 7)	123	°C/W
-		Thermal Registeres, Junction to Case	MSOP-8 (Note 5, 7)	33	C/VV
R <sub>θJC</sub>	Thermal Resistance, Junction to Case TSOT25 (Note 6, 7)		32	1	

Notes: 4. Stresses greater than the 'Absolute Maximum Ratings' specified above may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

5. External capacitors need to be connected to the output, EVM board was tested with external capacitor. This level is a pass test only and not a limit.

6. Test condition for TSOT25/MSOP-8: Device mounted on 1"x1"/2"x2" FR-4 substrate PC board, 2oz copper with minimum recommended pad layout. 7. R0JA and R0JC are measured at  $T_A = 25^{\circ}$ C on a high effective thermal conductivity four-layer test board per JEDEC 51-7.

## Recommended Operating Conditions (@ T<sub>A</sub> = +25°C, unless otherwise specified.) (Note 8)

Symbol	Parameter		Min	Max	Unit
V <sub>IN</sub>	Input Voltage	Input Voltage		5.5	V
	I <sub>OUT</sub> Output Current	AP22816	0	1.0	
IOUT		AP22817	0	1.5	A
		AP22818	0	2.0	
VIL	EN/EN Input Logic Low Voltage		0	0.5	V
VIH	EN/EN Input Logic High Voltage		1.5	VIN	V
TA	Operating Ambient T	Operating Ambient Temperature		+85	°C

8. Refer to the typical application circuit. Note:



Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
VUVLO	Input UVLO	V <sub>IN</sub> Rising		2.3	2.6	V
$\Delta V_{UVLO}$	Input UVLO Hysteresis	V <sub>IN</sub> Decreasing	_	180	_	mV
I <sub>SHDN</sub>	Input Shutdown Current	Disabled, OUT = Open	_	0.1	1	μA
lq	Input Quiescent Current	Enabled, OUT = Open	_	80	_	μA
I <sub>LEAK</sub>	Input Leakage Current	Disabled, OUT Grounded	_	0.1	1	μA
I <sub>REV</sub>	Reverse Leakage Current	Disabled, $V_{IN} = 0V$ , $V_{OUT} = 5V$ , $I_{REV}$ at $V_{IN}$	—	0.01	1	μA
R <sub>DS(ON)</sub>	Switch On-Resistance	$V_{IN} = 5V, I_{OUT} = 1A$ $T_A = +25^{\circ}C$	—	75	95	mΩ
		V <sub>IN</sub> = 5V, V <sub>OUT</sub> = 4.5V(AP22818)	2.2	2.7	3.2	Α
ILIMIT	Over Load Current Limit	V <sub>IN</sub> = 5V, V <sub>OUT</sub> = 4.5V(AP22817)	1.65	2.2	2.8	Α
		V <sub>IN</sub> = 5V, V <sub>OUT</sub> = 4.5V(AP22816)	1.1	1.5	2.1	А
I <sub>SHORT</sub>	Short-Circuit Current Limit	Enabled, Output short to ground	_	0.5	_	Α
VIL	EN/EN Input Logic Low Voltage	V <sub>IN</sub> = 2.7V to 5.5V	—	—	0.5	V
VIH	EN/EN Input Logic High Voltage	V <sub>IN</sub> = 2.7V to 5.5V		—	_	V
ILEAK-EN/EN	EN/EN Input Leakage	$V_{IN} = 5V, V_{EN/\overline{EN}} = 0V$ and 5.5V		0.01	1	μA
I <sub>LEAK-O</sub>	Output Leakage Current	Disabled, V <sub>OUT</sub> = 0V		0.5	1	μA
t <sub>D(ON)</sub>	Output Turn-On Delay Time	$C_L = 4.7 \mu F$ , $R_{LOAD} = 10\Omega @ V_{IN} = 3.3V$ Figure 1		1.5	_	ms
t <sub>R</sub>	Output Turn-On Rise Time	$C_L = 4.7 \mu F$ , $R_{LOAD} = 10\Omega @ V_{IN} = 3.3V$ Figure 1		2.1	3.5	ms
tD(OFF)	Output Turn-Off Delay Time	$C_L = 4.7 \mu F$ , $R_{LOAD} = 10\Omega$ @ $V_{IN} = 3.3V$ Figure 1	—	20	_	μs
tF	Output Turn-Off Fall Time	$C_L = 4.7 \mu F$ , $R_{LOAD} = 10\Omega$ @ $V_{IN} = 3.3V$ Figure 1	—	0.15	_	ms
R <sub>FLG</sub>	FLG Output FET On-Resistance	I <sub>FLG</sub> = 10mA	—	30	60	Ω
I <sub>FOH</sub>	FLG Off Current	V <sub>FLG</sub> = 5V	—	0.01	1	μA
t <sub>BLANK</sub>	FLG Blanking Time	Assertion or deassertion due to overcurrent and overtemperature condition	2	5	15	ms
t <sub>DIS</sub>	Discharge Time	$C_L = 1\mu F$ , $V_{IN} = 5V$ , disabled to $V_{OUT} < 0.5V$	—	0.4	_	ms
R <sub>DIS</sub>	Discharge Resistance	V <sub>IN</sub> = 5V, Disabled, I <sub>OUT</sub> = 1mA		140	200	Ω
T <sub>SHDN</sub>	Thermal Shutdown Threshold	Enabled		+150	_	°C
T <sub>HYS</sub>	Thermal Shutdown Hysteresis			+40	_	°C
V <sub>RVP</sub>	Reverse-Voltage Comparator Trip Point	V <sub>OUT</sub> - V <sub>IN</sub>		70	105	m۷
IROCP	Reverse Current Limit	$V_{OUT} - V_{IN} = 150 \text{mV}$		350		mA
t <sub>TRIG</sub>	Time from Reverse-Voltage Condition to MOSFET Turn off	V <sub>IN</sub>	2	5	15	ms

## **Performance Characteristics**

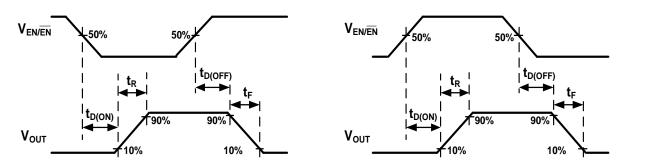
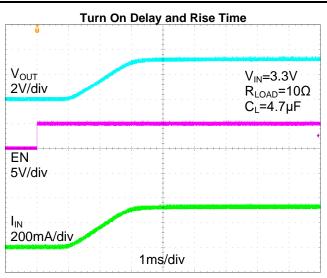
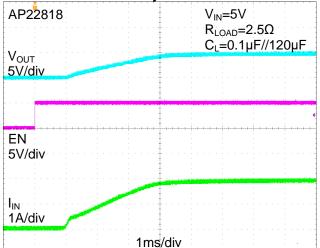


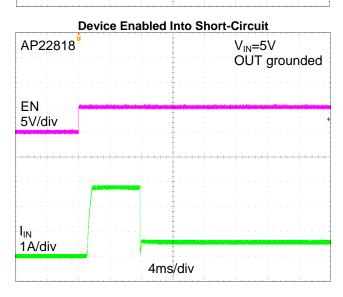
Figure 1. Voltage Waveforms: AP22816B (Active Low, Left), AP22816A (Active High, Right)

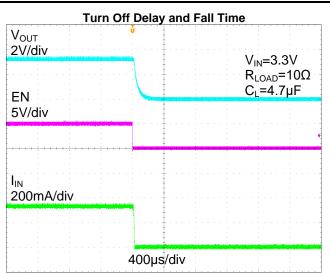


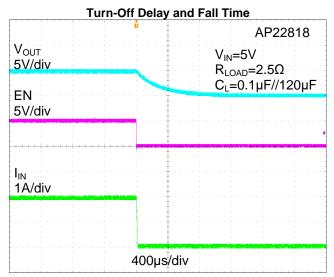


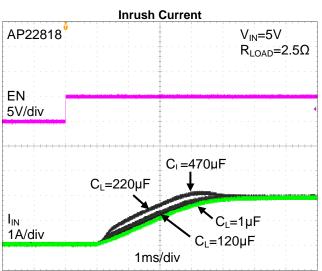
Turn-On Delay and Rise Time





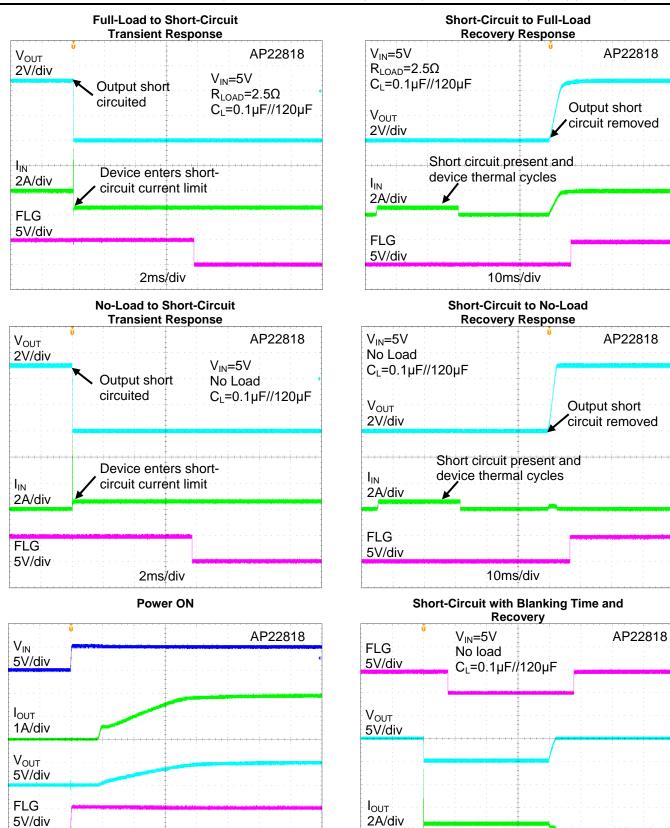






AP22816/17/18 Document number: DS43535 Rev. 3 - 2

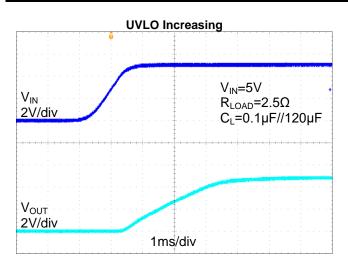


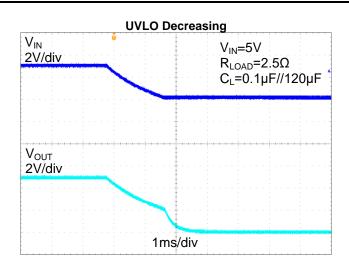


1ms/div

10ms/div



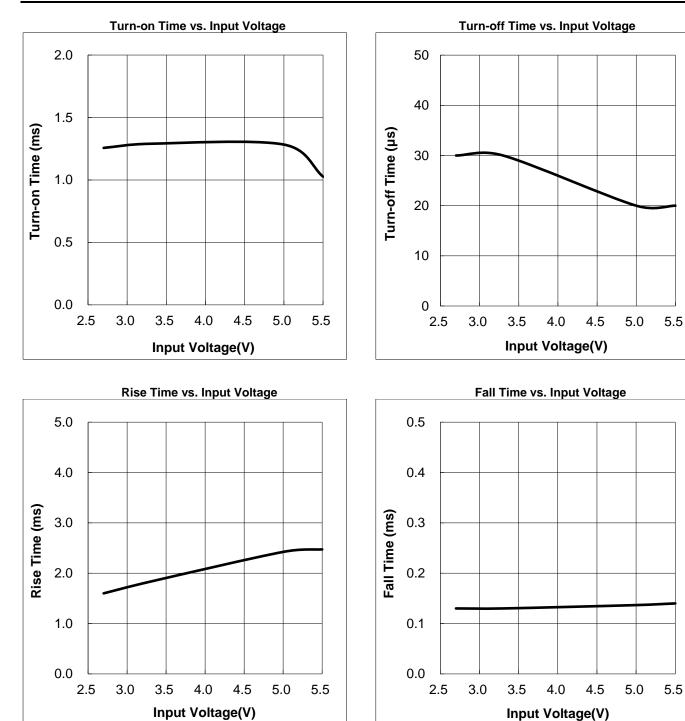




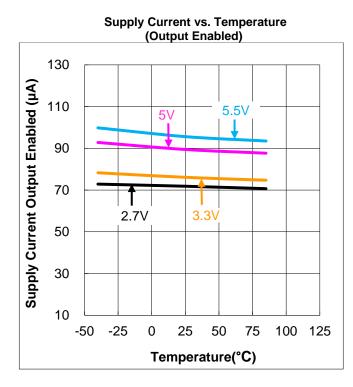
Re	Reverse-Voltage Protection Response				
V <sub>out</sub> 1V/div					
V <sub>IN</sub> 1V/div	5.5V Applied to V <sub>ουτ</sub>	V <sub>IN</sub> =5V R <sub>LOAD</sub> =10Ω C <sub>L</sub> =0.1μF//120μF			
I <sub>out</sub> 1A/div		Shutdown			
	2ms	/div			

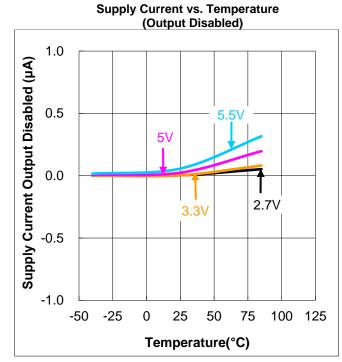
Revers	Reverse-Voltage Protection Recovery				
V <sub>out</sub> 1V/div	5.5V Removed from V <sub>ουτ</sub>				
V <sub>IN</sub> 1V/div	V <sub>IN</sub> =5V R <sub>LOAD</sub> =10Ω C <sub>L</sub> =0.1μF//120μ	١F			
I <sub>OUT</sub> 1A/div					
	2ms/div				

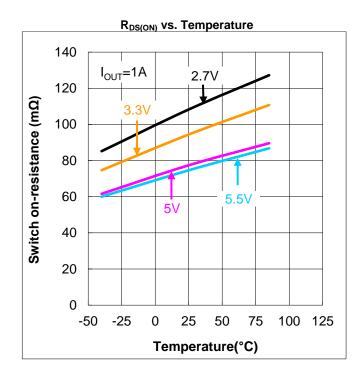




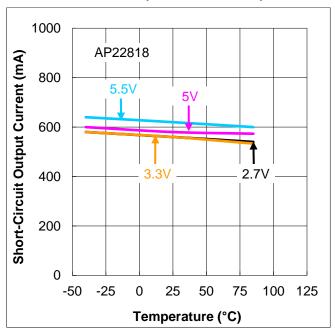




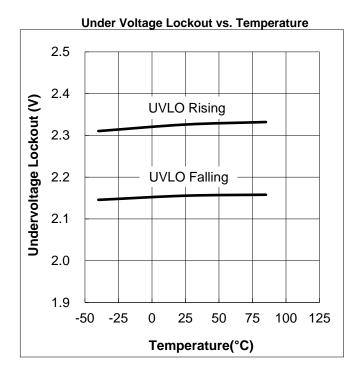




Short-Circuit Output Current vs. Temperature



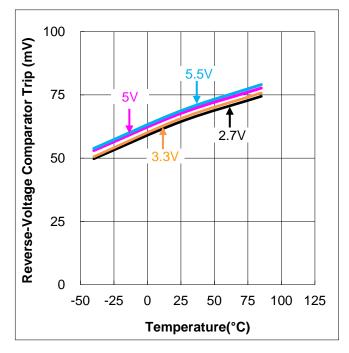




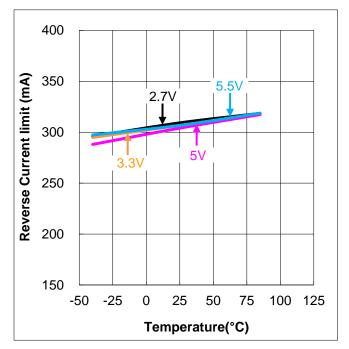
#### 3.2 AP22818 Over Load Current Limit (A) 3.0 2.8 5.5V 5V 2.6 Î 3.3\ 2.7V 2.4 2.2 -50 -25 0 25 50 75 100 125 Temperature(°C)

**Over Load Current Limit vs. Temperature** 

#### **Reverse-Voltage Comparator Trip vs. Temperature**



**Reverse Current Limit vs. Temperature** 





## **Application Information**

#### Input and Output Capacitors

It is needed to place a  $1\mu$ F X7R or X5R ceramic bypass capacitor between the IN and GND, close to the device. Placing a high-value capacitor ( $10\mu$ F or  $47\mu$ F) close to the input pin is also recommended when the output transient load is heavy. This precaution reduces power-supply transients that may cause ringing on the input.

Also needed for hot-plug applications is the connection of a minimum  $100\mu$ F low ESR electrolytic or tantalum capacitor (or  $10\mu$ F MLCC) between OUT and GND is. It is necessary to bypass the output with a  $0.1\mu$ F ceramic capacitor, which improves the immunity of the device to short-circuit transients. The Bulky  $100\mu$ F or larger capacitors help to reduce output droop voltage when a device is plugged in. When abnormal short-circuit condition happens, these capacitors can also reduce output negative voltage due to parasitic inductive effect and avoid device damage.

Please note that without the bypass capacitors, an output short may cause ringing on the input; if the voltage is over the maximum voltage rating, it will destroy the internal control circuitry even if the duration is short.

#### **FLG Response**

When an overcurrent or overtemperature shutdown condition is encountered, the FLG open-drain output goes active low after a nominal 6ms deglitch timeout. The FLG output remains low until both overcurrent and overtemperature conditions are removed. Connecting a heavy capacitive load to the output of the device can cause a momentary overcurrent condition, which does not trigger the FLG due to the 6ms deglitch timeout. The AP22816(1.0A)/17(1.5A)/18(2.0A) is designed to eliminate false overcurrent reporting without the need of external components to remove unwanted pulses.

#### **Overcurrent and Short Circuit Protection**

An internal sensing FET is employed to check for overcurrent conditions. Unlike current-sense resistors, sense FETs do not increase the series resistance of the current path. When an overcurrent condition is detected, the device maintains a constant output current and reduces the output voltage accordingly. Complete shutdown occurs only if the fault stays long enough to activate thermal limiting.

Three possible overload conditions can occur. In the first condition, the output has been shorted to GND before the device is enabled or before  $V_{IN}$  has been applied. The AP22816(1.0A)/17(1.5A)/18(2.0A) senses the short circuit and immediately clamps output current to a certain safe level.

In the second condition, an output short or an overload occurs while the device is enabled. At the instance the overload occurs, higher current may flow for a very short period of time before the current limit function can react. After the current limit function has tripped, the device switches into current limiting mode and the current is clamped at ILIMIT, or ISHORT.

In the third condition, the load has been gradually increased beyond the recommended operating current. The current is permitted to rise until the current-limit threshold (I<sub>TRIG</sub>) is reached or until the thermal limit of the device is exceeded. The AP22816(1.0A)/17(1.5A)/18(2.0A) is capable of delivering current up to the current-limit threshold without damaging the device. Once the threshold has been reached, the device switches into its current limiting mode and is set at I<sub>LIMIT</sub>.

#### **Thermal Protection**

Thermal protection prevents the IC from damage when heavy-overload or short-circuit faults are present for extended periods of time. The AP22816(1.0A)/17(1.5A)/18(2.0A) implements a thermal sensing to monitor the operating junction temperature of the power distribution switch. Once the die temperature rises to approximately +140°C due to excessive power dissipation in an overcurrent or short-circuit condition, the internal thermal sense circuitry turns the power switch off, thus preventing the power switch from damage. Hysteresis is built into the thermal sense circuit allowing the device to cool down approximately +35°C before the switch turns back on. The switch continues to cycle in this manner until the load fault or input power is removed. The FLG open-drain output is asserted when an overtemperature shutdown or overcurrent occurs with 6ms deglitch.

#### **ON/OFF Input Operator**

The EN/EN input allows the output current to be switched on and off using a GPIO compatible input. The high signal (switched on) should be at least 1.5V, and the low signal (switch off) no higher than 0.65V. This pin should not be left floating. It is advisable to hold the EN/EN signal low when applying or removing power.



## Application Information (continued)

#### Undervoltage Lockout (UVLO)

Undervoltage lockout function (UVLO) keeps the internal power switch from being turned on until the power supply has reached at least 2V, even if the switch is enabled. Whenever the input voltage falls below approximately 2V, the power switch is quickly turned off. This facilitates the design of hot-insertion systems where it is not possible to turn off the power switch before input power is removed.

#### **Discharge Function**

The discharge function of the device is active when the enable is disabled or de-asserted. The discharge function with the N-MOS power switch implementation is activated and offers a resistive discharge path for the external storage capacitor. This is designed for discharging any residue of the output voltage when either no external output resistance or load resistance is present at the output.

#### **Output Reverse-Voltage/Current Protection**

The output reverse-voltage protection turns off the MOSFET switch whenever the output voltage is higher than the input voltage by 50mV for 6ms. The MOSFET switch will turn on when output reverse-voltage/current conditions are removed.

#### **Power Dissipation and Junction Temperature**

The low on-resistance of the internal MOSFET allows the small surface-mount packages to pass large currents. Using the maximum operating ambient temperature (T<sub>A</sub>) and R<sub>DS(ON)</sub>, the power dissipation can be calculated by:

 $P_D = R_{DS(ON)} \times I^2$ 

Finally, calculate the junction temperature:

 $T_J = P_D \times R_{\theta JA} + T_A$ 

Where:  $T_A$  = Ambient temperature °C  $R_{\theta JA}$  = Thermal resistance  $P_D$  = Total power dissipation

#### **Board Layout Instruction**

To minimize the effects of parasitic inductance, place input and output capacitors (1µF and 0.1µF+100µF respectively) close and next to the device's pins. For the best performance, all trace lengths should be kept as short as possible and the input and output PCB traces should be as wide as possible. Use a ground plane to enhance the power dissipation capability of the device. For TOS25 Type KB and MSOP-8, it is recommended to connect all IN pins together and all OUT pins together to improve overall resistance value.



# Ordering Information

AP2281 <u>X</u>	×	<u>xx</u>	<u>xx</u>	- <u>x</u>
Current Rating 6 : 1.0A 7 : 1.5A 8 : 2.0A	Enable A : Active High B : Active Low	Pin Definition K/KA/KB/KCKE: TSOT25	Package WT: TSOT25 M8: MSOP-8	Packing -7 : Tape & Reel -13 : Tape & Reel

De ef Niemele en	Deckers Code	Package	7" and 13" Tape and Reel		
Part Number	Package Code		Quantity	Part Number Suffix	
AP22816AKWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816BKWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816AKAWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816BKAWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816AKBWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816BKBWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816AKCWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816BKCWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816AKEWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22816BKEWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817AKAWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817BKAWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817AKBWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817BKBWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817AKCWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817BKCWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817AKEWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22817BKEWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818AKWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818BKWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818AKAWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818BKAWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818AKBWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818BKBWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818AKCWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818BKCWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818AKEWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818BKEWT-7	WT	TSOT25	3000/Tape & Reel	-7	
AP22818AM8-13	M8	MSOP-8	2500/Tape & Reel	-13	
AP22818BM8-13	M8	MSOP-8	2500/Tape & Reel	-13	



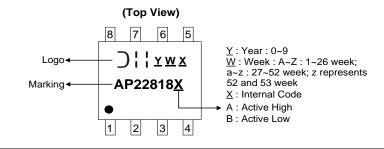
AP22816/17/18

# **Marking Information**

## (1) TSOT25

(Top View)		
5 XXX YWX 1 2		9 to Z : 1 to 26 week; 7 to 52 week; z represents 8 week
Part Number	Package	Identification Code
AP22816AKWT-7	TSOT25	F2A
AP22816BKWT-7	TSOT25	F2B
AP22816AKAWT-7	TSOT25	F2C
AP22816BKAWT-7	TSOT25	F2D
AP22816AKBWT-7	TSOT25	F2E
AP22816BKBWT-7	TSOT25	F2F
AP22816AKCWT-7	TSOT25	F2G
AP22816BKCWT-7	TSOT25	F2H
AP22816AKEWT-7	TSOT25	F2J
AP22816BKEWT-7	TSOT25	F2K
AP22817AKAWT-7	TSOT25	F2M
AP22817BKAWT-7	TSOT25	F2N
AP22817AKBWT-7	TSOT25	F2P
AP22817BKBWT-7	TSOT25	F2R
AP22817AKCWT-7	TSOT25	F2S
AP22817BKCWT-7	TSOT25	F2T
AP22817AKEWT-7	TSOT25	F2U
AP22817BKEWT-7	TSOT25	F2V
AP22818AKWT-7	TSOT25	F2W
AP22818BKWT-7	TSOT25	F2X
AP22818AKAWT-7	TSOT25	F2Y
AP22818BKAWT-7	TSOT25	F2Z
AP22818AKBWT-7	TSOT25	F22
AP22818BKBWT-7	TSOT25	F23
AP22818AKCWT-7	TSOT25	F24
AP22818BKCWT-7	TSOT25	F25
AP22818AKEWT-7	TSOT25	F26

### (2) MSOP-8



TSOT25

F27

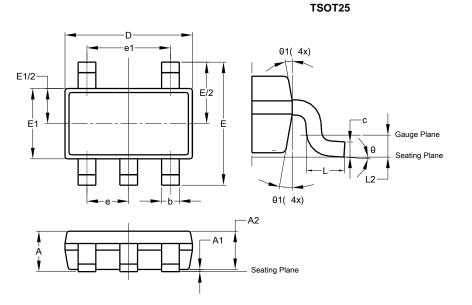
AP22818BKEWT-7

Part Number	Package	Identification Code
AP22818AM8-13	MSOP-8	AP22818A
AP22818BM8-13	MSOP-8	AP22818B



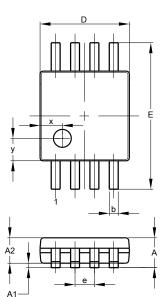
# **Package Outline Dimensions**

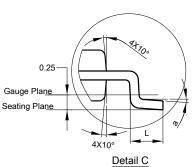
Please see http://www.diodes.com/package-outlines.html for the latest version.

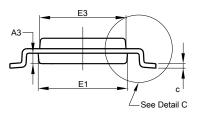


TSOT25					
Dim	Min	Max	Тур		
Α	-	1.00	-		
A1	0.01	0.10	-		
A2	0.84	0.90	-		
b	0.30	0.45	-		
С	0.12	0.20	-		
D	2.80	3.00	2.90		
Е	2.70	2.90	2.80		
E1	1.50	1.70	1.60		
е	0.95 BSC				
e1	1.90 BSC				
L	0.30	0.50			
L2	0.25 BSC				
θ	0°	8°	4°		
θ1	4°	12°	-		
All Dimensions in mm					

MSOP-8







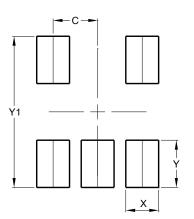
MSOP-8					
Dim	Min	Max	Тур		
Α	-	1.10	-		
A1	0.05	0.15	0.10		
A2	0.75	0.95	0.86		
A3	0.29	0.49	0.39		
b	0.22	0.38	0.30		
С	0.08	0.23	0.15		
D	2.90	3.10	3.00		
E	4.70	5.10	4.90		
E1	2.90	3.10	3.00		
E3	2.85	3.05	2.95		
е	-	-	0.65		
L	0.40	0.80	0.60		
а	0°	8°	4°		
х	-	-	0.750		
у	-	-	0.750		
All	All Dimensions in mm				



# **Suggested Pad Layout**

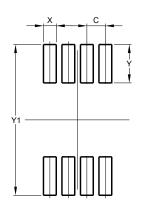
Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT25



Dimensions	Value (in mm)	
С	0.950	
Х	0.700	
Y	1.000	
Y1	3.199	

MSOP-8



 
 Dimensions
 Value (in mm)

 C
 0.650

 X
 0.450

 Y
 1.350

 Y1
 5.300



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